



JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD

TO-220BK Plastic-Encapsulate Thyristors

CT416B 4Q TRIACs

MAIN CHARACTERISTICS

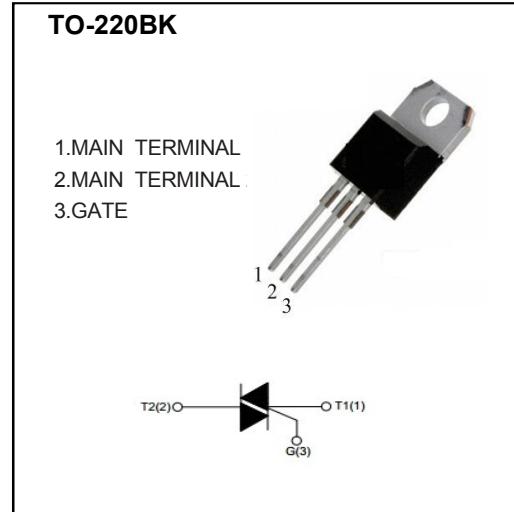
I _{T(RMS)}		16A
V _{DRM} /V _{RRM}	CT416B-600S/C/B	600V
	CT416B-800S/C/B	800V
V _{TM}		1.55V

FEATURES

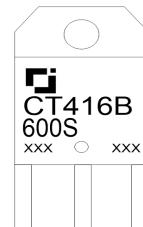
- NPNPN 5-layer Structure TRIACs
- Mesa Glass Passivated Technology
- Multi Layers Metal Electrodes
- High Junction Temperature
- Good Commutation Performance
- High dV/dt and dl/dt

APPLICATIONS

- Heater Control
- Motor Speed Controller
- Mixer



MARKING



CT416B:Series Code

600S:Depends on V_{DRM} and IGT

XXX:Internal Code

ABSOLUTE RATINGS (T_a=25°C unless otherwise noted)

Symbol	Parameter	Test condition		Value		Unit
V _{DRM} / V _{RRM}	Repetitive peak off-state voltage	T _j =25°C	CT416B-600S/C/B	600		V
			CT416B-800S/C/B	800		V
I _{T(RMS)}	RMS on-state current	TO-220BK(T _C ≤110°C), Fig. 1,2		16		A
I _{TSM}	Non repetitive surge peak on-state current	Full sine wave , T _{j(init)} =25°C, tp=20ms; Fig. 3,5		160		A
I ² t	I ² t value	tp=10ms		140		A ² s
dI _T /dt	Critical rate of rise of on-state current	I _G =2*I _{GT} , tr≤10ns, F=120Hz, T _j =125°C	I - II - III	50		A/μs
			IV	10		
I _{GM}	Peak gate current	tp=20μs, T _j =125°C		4		A
P _{G(AV)}	Average gate power	T _j =125°C		1		W
T _{STG}	Storage temperature			-40~+150		°C
T _j	Operating junction temperature			-40~+125		

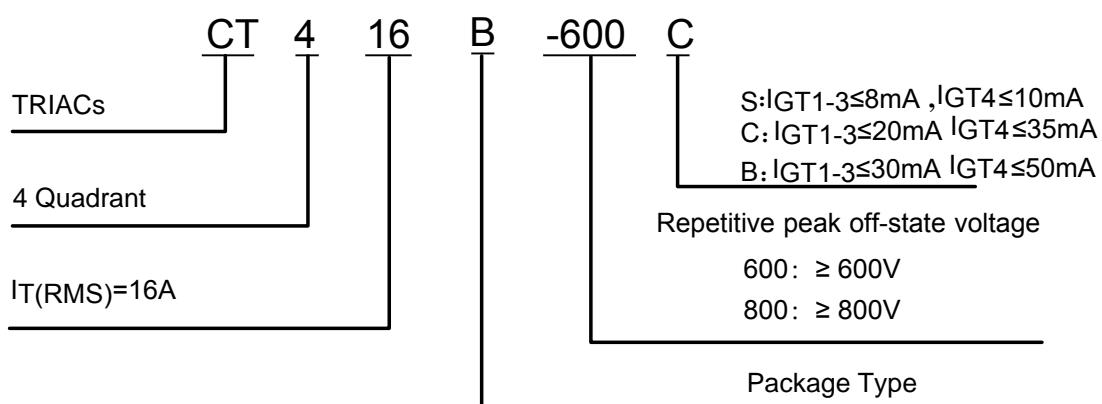
ELECTRICAL CHARACTERISTICS ($T_a=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test condition	Value			Unit	
			S	C	B		
I_{GT}	Gate trigger current	$V_D=12\text{V}$, $R_L = 33\Omega$, $T_j=25^\circ\text{C}$, Fig. 6	I - II - III	≤ 8	≤ 20	≤ 30	mA
			IV	≤ 10	≤ 35	≤ 50	
V_{GT}	Gate trigger voltage	$V_D=V_{DRM}$, $T_j=125^\circ\text{C}$	I - II - III		≤ 1.3		V
V_{GD}	Non-triggering gate voltage		≥ 0.2			V	
I_H	Holding current	$V_D=12\text{V}$, $I_{GT}=0.1\text{A}$, $T_j=25^\circ\text{C}$, Fig. 6	I - II - III - IV	≤ 10	≤ 25	≤ 30	mA
I_L	Latching current		I - III - IV	≤ 15	≤ 30	≤ 40	mA
			II	≤ 20	≤ 40	≤ 70	mA
dV_D/dt	Critical rate of rise of off-state	$V_D=67\%V_{DRM}$, Gate Open $T_j=125^\circ\text{C}$		≥ 10	≥ 20	≥ 50	V/ μs
V_{TM}	On-state Voltage	$I_{TM}=20\text{A}$ tp=380 μs , Fig. 4		≤ 1.55		V	
I_{DRM} / I_{RRM}	Repetitive peak off-state current	$V_D=V_{DRM}/V_{RRM}$, $T_j=25^\circ\text{C}$		≤ 5	≤ 5	≤ 5	μA
		$V_D=V_{DRM}/V_{RRM}$, $T_j=125^\circ\text{C}$		≤ 1	≤ 1	≤ 1	mA

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th} (j-c)$	Junction to case (AC)	1.2	°C/W
$R_{th} (j-a)$	Junction to ambient	60	°C/W

PART NUMBER



CHARACTERISTICS CURVES

FIG.1: Maximum power dissipation versus RMS on-state current (full cycle)

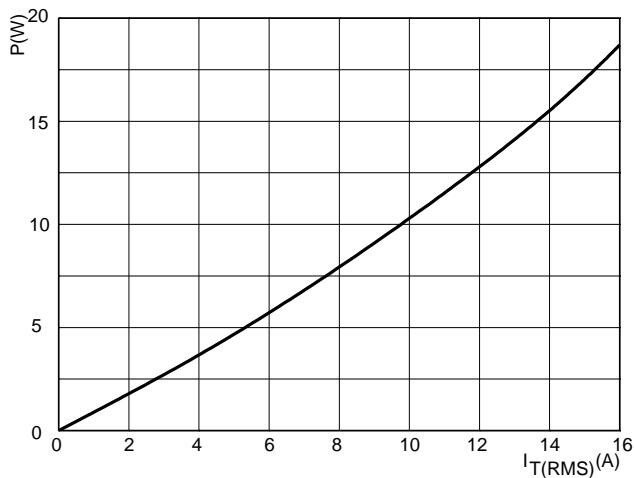


FIG.2: RMS on-state current versus case temperature (full cycle)

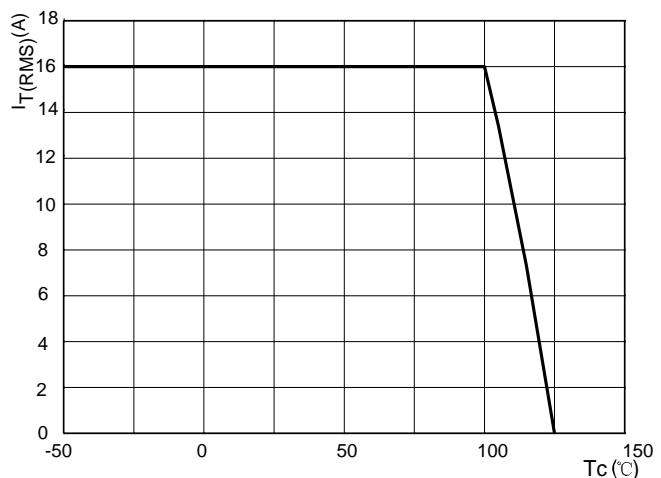


FIG.3: Surge peak on-state current versus number of cycles

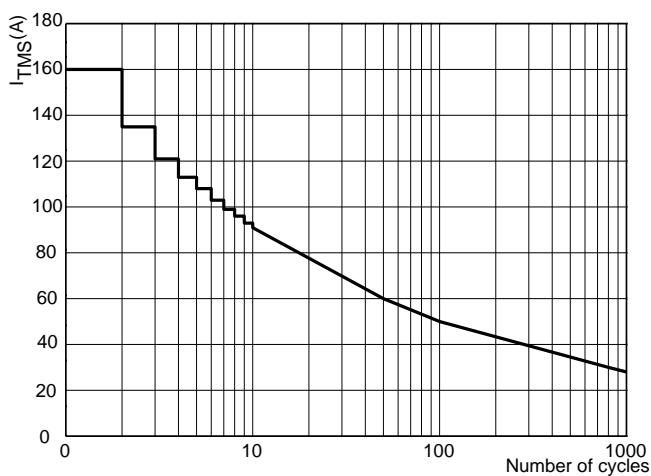


FIG.4: On-state characteristics (maximum values)

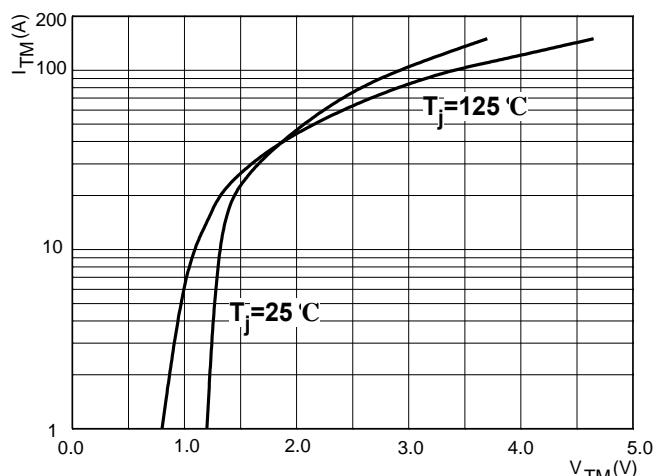


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ms}$

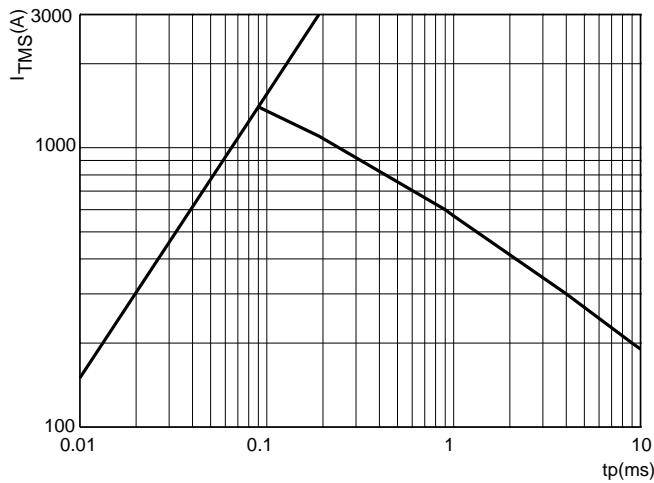
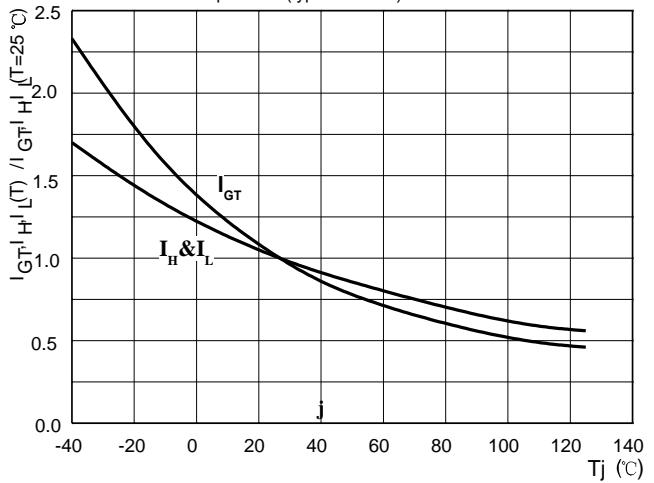
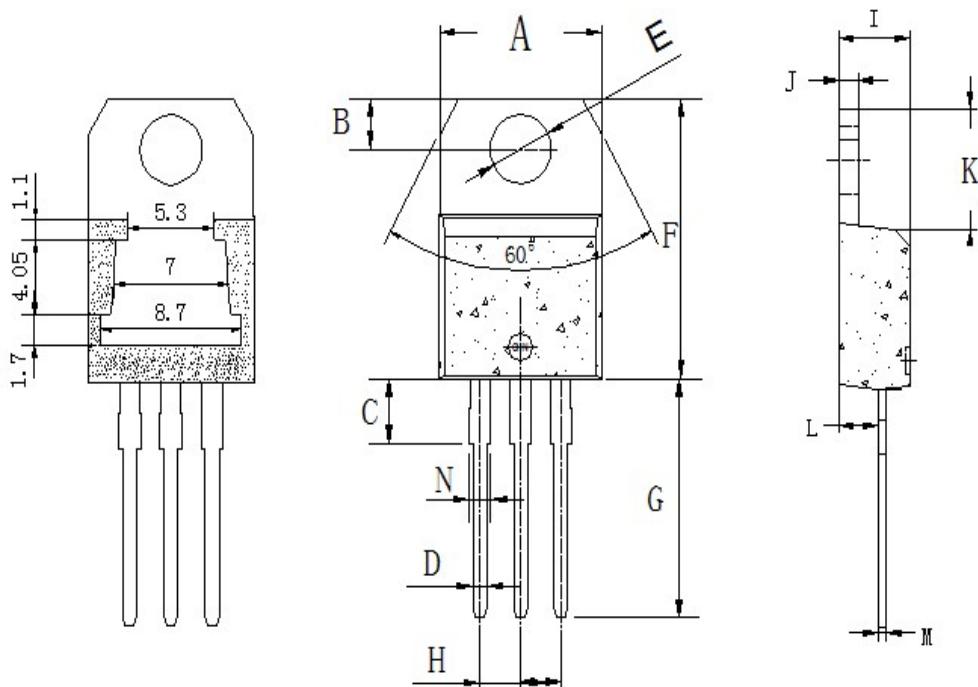


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature (typical values)



TO-220BK PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	9.8	10.4	0.385	0.409
B	2.65	3.1	0.104	0.122
C	2.8	4.2	0.110	0.165
D	0.7	0.92	0.027	0.036
E	3.75	3.95	0.147	0.155
F	14.8	16.1	0.582	0.633
G	13.05	13.6	0.513	0.535
H	2.4	2.7	0.094	0.106
I	4.38	4.61	0.172	0.181
J	1.15	1.36	0.045	0.053
K	5.85	6.82	0.230	0.268
L	2.35	2.75	0.092	0.108
M	0.35	0.65	0.013	0.025
N	1.18	1.42	0.046	0.055